

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory		User Part Number BZX84-C16 Part Description												
										Nexperia DHAM	Zener			
								Assembly reliability labs Based on AEC-Q101 Test		SMD package				
Test Conditions	Duration	# Lots	# Quantity	# Rejects										
	TEST													
	Pre- and Post-Stress													
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below								
		JESD22-A113	241											
	PC	Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	24 hours 168 hours											
# A1	Preconditioning	Reflow soldering	3 cycles	810	58300	0								
		MIL-STD-750-1	•			-								
	HTRB	M1038 Method A												
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet												
# B1	Bias	reverse voltage	1000 hours	138	11040	0								
		MIL-STD-750-1												
		M1038 Method B												
	SSOP	Tj = Tjmax, Iz = 100% of max. datasheet				_								
# B1b	Steady State Operational	reverse current	1000 hours	20	1600	0								
	тс	JESD22-A104												
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	170	13600	0								
# A4	remperature cycling	JESD22-A102	1000 Cycles	170	13000	0								
	AC	Tamb = 121 °C, RH = 100 %												
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0								
	H3TRB	JESD22-A101												
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of												
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^[1]	1000 hours	170	13600	0								
		MIL-STD-750 Method 1037												
	IOL	ton = toff, devices powered to insure ΔTj =												
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	170	13600	0								
	RSH	JECD22 A111												
# C8	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10.0	120	2000	0								
+ C8	SD	200 0 = 3 0	10 s	130	3900	U								
# C10	Solderability	J-STD-002		363		0								

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11040	0	0.38	2.60E+09

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